





# Electron, Muon and Charged Hadron PID systems for detectors of the 2030s and 2040s

Angela Romano, University of Birmingham

ECFA-UK Meeting on UK studies for the European Strategy for Particle Physics Update 23-26 September 2024, IPPP Durham



angela.romano@cern.ch



### UNIVERSITY<sup>OF</sup> BIRMINGHAM



### Electron, Muon and Charged Hadron PID systems

- Focus on UK contributions (current and opportunities) to detector R&D for
  - Particle Identification (DRD4)
  - Calorimetry (DRD6)
  - Gaseous detectors (DRD1)
- R&D in line with Task Forces established by ECFA detector R&D roadmap
- Milestones supported by international DRD collaborations
- In the context of major projects foreseen for 2030s and 2040s
  - ➢ LHCb Upgrade II, ALICE III, EpIC, FCCee, Super Tau-Charm Facility (STCF), ...

.... not exhaustive list of projects !

DISCLAIM



The different priorities of the physics projects is not topic for this talk → the relative importance of proposed detector R&D activities to these projects is the main aspect that will be discussed

Liquid detectors (DRD2) → see Roxanne's talk Solid state detectors (DRD3) → see Eva's talk Quantum technology (DRD5) → see Ed's talk Electronics (DRD7) → see Connor's talk

### Main Drivers for PID detectors of 2030s/40s

From ECFA DRD Roadmap 2020

- Wide range of **primary drivers for PID detectors** in future PP experiments
- Flavour physics experiments (LHCb, Belle II, NA62 and future kaon experiments, FCC-ee..) rely on PID to fulfil their physics goals
- New PID techniques important for hadronic and heavy-ion experiments (ALICE, EIC, PANDA..)
- Development of **RICH (Ring Imaging CHerenkov)** and **DIRC (Detectors for Internally Reflected Cherenkov light)** technology is essential for experiments where PID is paramount
- **Time of flight (TOF)** is also important and usually provides low-momentum coverage complementary to RICH information.
- Picosecond timing is an important theme running throughout all future PP applications,

UK leadership and track record in PID detectors (e.g. LHCb RICH, NA62 KTAG) UK leading contributions to exciting R&D on PID for future experiments (including but not limited to LHCb U2, FCC-ee, ..)

# The LHCb Upgrade 2



European Strategy Update 2020:

"The full potential of the LHC and the HL-LHC, including the study of flavour physics, should be exploited"

### LHCb Upgrade 2 – PID Systems



New TORCH (Time of internally reflected Cherenkov light) for charged hadron ID in low momentum range from 2-10 GeV/c

➔ H. Cliff PPAP Community Meeting 25-06-2024

UK contributions to PID (RICH and TORCH) and tracking (VELO, Mighty Tracker)

Design challenges posed by the high luminosity:

- Higher granularity, need for non-uniform detectors to cope with busier events
- Radiation-hard detectors to survive intense conditions
- Fast timing to separate overlapping pp interactions



Electron, muon, and charged hadron identification essential to target a broad Flavour Physics programme

al to toward a law and Elawarm Dhy

# LHCb Upgrade 2 – Timing

4D measurement (time and space coordinates) well established technique in current fixed-target kaon experiment at CERN  $\rightarrow$  NA62 beam tracker, PID systems and calo provide ~100ps time resolution across the detector

### Fast timing crucial to reduce backgrounds in HL-LHC environment

O(10 ps) time resolution per particle allows charged tracks and photons to be associated to the correct PV



Design challenges posed by high luminosity are shared amongst all HL-LHC experiments

LHC bunches are long (50mm) and pp interactions occur over 0.2 ns

### VELO tracker, RICH, TORCH and eCAL (picoCal) will be fast timing detectors:

- Add new dimension to information exchanged between sub-detectors
- > Create potential for data suppression in front-end hardware and software trigger
- Set challenging R&D requirements, particularly for sensors and front-end ASICs

### The LHCb RICH

### **RICH system in Run1 & Run2**

- □ RICH 1 ( $C_4F_{10}$ ): upstream, 2 GeV/c 40 GeV/c over 25 mrad 300 mrad
- RICH 2 (CF<sub>4</sub>): downstream, 15 GeV/c 100 GeV/c
   over 15 mrad 120 mrad

### **Upgrades:**

- □ Upgrade I operating from Run 3
- □ Enhancement foreseen in LS3 for Run 4
- □ Upgrade 2 expected in LS4 for HL-LHC ( $\geq$  Run5)

### The challenge for Upgrade 2:

 Maintain same excellent PID performance of Run3 in fierce environment of high-luminosity operation

### **Key specifications for Upgrade 2:**

 Improve Cherenkov angle resolution (<0.5mrad) and keep peak occupancy under ~ 30%





Single event in RICH1 at different pile-up levels

# LHCb Upgrade 2 - RICH - Timing

Reconstructed parameters in RICH algorithms and PV t<sub>0</sub>, can predict the detector hit times to within 10 ps



Time gate around the predicted time significantly reduces combinatorial background (and peak occupancy) and helps to recover the same PID performance as in Run 3

Time gate width depends on photon detector resolution  $\rightarrow$  aim for a resolution  $\sigma_t(\gamma) < 100$  ps

Huge R&D campaigns on fast Photon Detectors (SiPMs, MCP based, next gen MaPMTs) and fast Electronics (fastIC, picoTDC, fastRICH ASIC)

### R&D for LHCb RICH Enhancement in LS3

- timing concept new to LHCb but common amongst many systems for LHCb upgrade II
- anticipate ASIC development to LS3: introduce time stamp of photons
- FastRICH ASIC fast enough to be used in upgrade II
   ⇒ timing in Run4 limited by photon detectors
- improvement in PID performance expected already in Run4
- LS3 PID TDR [CERN-LHCC-2023-005] approved in March 2024





### FastRICH designed in UK



#### Shared interest and close collaboration with DRD4

## R&Ds for RICH in LHCb Upgrade 2

#### Road to optimization of the Cherenkov angle resolution $\rightarrow$ goal is <0.5 mrad

Explore modifications to RICH optics and mechanics:

- → Reduce tilt of spherical mirrors, add flat mirrors in LHCb acceptance, reduce emission point error
- → R&D on carbon fibre flat mirrors, light-weight supports and with good resistance to radiation

Studies of low refractive index radiators (fluorocarbon gases) for relatively low chromatic dispersion
 → the chromatic error depends on the convolution between the dispersion and the photon detector QE
 → R&D on new gas mixtures, eco-friendly alternatives, and innovative metamaterials
 → R&D investigating photocathodes (SiPMs) shifted towards the green to reduce single-photon chromatic error

Operating conditions for the LHCb Upgrade II will result in unprecedented conditions for a RICH detector concerning high track and hit densities and radiation environment

R&D ongoing on optics, radiators, photon detectors, fast electronics, mechanics to achieve the ultimate performance of a RICH detector in a high-luminosity environment

Very challenging programme with plenty of room for synergies with other R&D campaigns Close collaboration with international DRD4 programme in all areas

# The LHCb Time Of Flight - TORCH

#### **TORCH (Time Of internally Reflected CHerenkov light):**

- Large area DIRC-type TOF detector designed to provide PID in the 2–15 GeV/c momentum range.
- Supplement PID performance in momentum region where K/ $\pi$  are below threshold in LHCb RICH detectors.
- Aiming for installation as part of LHCb Upgrade 2 [CERN-LHCC-2017-003]
- Highly-polished 1 cm thick quartz plate used as radiator
- Photons internally reflected and focussed onto photon detectors.
- Similar DIRC concept of Belle 2 TOP detector
- Chromatic dispersion corrected and arrival time of photons measured precisely

#### **Requirements:**

- ✓ At 10 metres from collision point, per track resolution of 15 ps for  $3\sigma$  K/ $\pi$  separation (per photon resolution of 70 ps)
- ✓ Large area detector to cover the full LHCb acceptance (5x6 m<sup>2</sup>).
- ✓ High-quality surface on front and rear faces (flatness variation ≤  $3\mu$ m and surface roughness 5Å.
- $\checkmark$  Light-weight carbon fibre support structure inside detector acceptance to minimise  $X_0$



# **TORCH Photon Detectors**

Current TORCH prototype uses custom 53x53mm<sup>2</sup> MCP-PMTs with 64x64 pads [JINST 10 (2015) C05003]

- Excellent intrinsic time resolution (< 30 ps).</p>
- ✤ MCP is ALD coated for a lifetime > 5C/cm<sup>2</sup>
- Pads modified to form 8x64 pixel arrangement

Ongoing R&D within DRD4 to improve rate capability and lifetime (ideally well beyond 10C/cm<sup>2</sup>) Strong synergies between LHCb RICH, TORCH, Belle 2, future kaon experiments and PID detectors @ ePIC and FCC-ee

<u>Opportunity for UK to lead the MCP-PMT developments</u> by exploiting the consolidated connection with Photek

For electronics plan to use FastRICH ASIC. Common development possible for LHCb TORCH and RICH applications







re Production of customized MCP-PMTs through collaboration with UK industrial partner Photek Ltd



T. Blake @ Pisa Meeting in Elba 2024

# R&Ds for TORCH in LHCb Upgrade 2

- Production of customized MCP-PMTs through collaboration with industrial partner Photek Ltd
- Prototype tests of half-sized TORCH module equipped with Photek customized MCP-PMTs indicate that desired time resolution can be achieved ( $\sigma_t(\gamma) \sim 70$  ps).
- Aim to assemble a full-scale prototype with light-weight support to be tested at the CERN PS in 2025.

Near-future R&D: construct a full-sized TORCH module, fully equipped with 11 Photek customized MCP-PMTs and light-weight support. The module could be installed in LHCb experiment during LS3.

Future R&D: next-generation high-granularity MCP-PMTs will be developed with Photek and equipped with new-generation of fast electronics

R&D ongoing within DRD4 to develop: MCP-PMTs with increased lifetime; lightweight mechanics; systems to qualify the surface finish of the large area fused-silica radiators.

#### Shared interests and close collaboration with international DRD4

# ALICE 3 (2035+)

Compact and lightweight all-silicon tracker Retractable vertex detector Extensive particle identification capability Larger pseudorapidity acceptance Superconducting magnet system

Continuous readout and online processing

#### ALICE 3 PID system:

Time-Of-Flight: InnerTOF, OuterTOF, Forward TOF disks Ring-Imaging Cherenkov: Barrel RICH, Forward RICH EM Calorimeter: Barrel + Forward ECAL Muon Identifier Detector: Barrel Muon Identification Detector



P. Jones @ PPAP Community Meeting June 2024

ALICE 2: UK leadership in trigger and track record in Silicon detector design & construction ALICE 3: Proposed UK involvement in outer tracking and triggering

### The ePIC Detector @ EIC

Expect construction approval in 2025 and start of operations in 2034



#### UK involvement funded through the UKRI Infrastructure Fund

- Magnet and Tracking 
   → UK contribution to tracking systems
  - 1.7 T solenoid
  - Micro-Rwell and Micro-Megas
  - Si-MAPS
- Calorimetry
- Barrel Imaging Calorimeter
- e-Cap: PbWO4 EMCal
- Forward: finely segmented EMCal and hCal

### PID

#### Backward

Proximity focusing RICH (aerogel RICH + peripheral conical mirrors + HRPPD) Central

Time Of Flight (AC LGAD), DIRC (fused silica bar with novel lensing and MCP-PMT based readout)

#### Forward

Time Of Flight (AC LGAD) and Dual radiator RICH (aerogel + C2F6 gas + spherical mirrors + SiPM sensors)

UK (Glasgow) is also part of eRD110: a photosensor R&D program for EIC funded by JLab eRD110: Characterisation of Photek MCP-PMT (for DIRC) and Incom HRPPD (high-rate large area MCP for pfRICH) Common goals and synergies with UK R&D on PID systems and photon detectors

# Array of RICH Cells @ FCC-ee

- Array of RICH Cells (ARC): A novel RICH detector concept
  - First presented by R. Forty at FCC week 2021
  - Compact, low-mass solution for particle ID for FCC-ee
  - Concept inspired by the compound eyes of an insect
- Adapted to fit into the CLD experiment concept, taking 10% from the tracker volume
  - Radial depth of 20 cm, radius of 2.1 m and a length of 4.4 m
  - Aim to keep material budget below  $0.1X_0$
- Aerogel and gas radiators with a spherical mirror
  - Aerogel also acts as thermal insulation between gas and detector



SiPMs current baseline photon detector technology considered

#### Future Project (2040+)

**Challenge:** achieve excellent hadron PID with compact, lightweight layout in a  $4\pi$  detector at e<sup>+</sup>e<sup>-</sup> collider (FCC-ee).

**Goal Performance:**  $3\sigma$  K- $\pi$  separation in the range 2-50 GeV/c

#### Importance of proposed detector:

- enable a rich Flavour Physics programme at FCCee
- enhance the capabilities in Higgs,
   WW and top physics (e.g. H decays to strange quarks)

R&D for ARC concept is a recognized goal of international DRD4 with deliverable: evaluation of a prototype ARC cell

### Silicon PhotoMultipliers (SiPMs)

SiPMs have several advantages:

- extremely fine granularity
- resilience to magnetic fields
- high photon detection efficiency
- good time resolution ( $\sim$  100 ps)



SiPMs are possible candidates for LHCb RICH Upgrade 2:

- used in green wavelength region to reduce single-photon chromatic correction
- improved granularity to 1.0 x 1.0 mm<sup>2</sup> pixels to reduce peak photon occupancy << 100%

SiPM application across all future PP experiments  $\rightarrow$  radiation hardness, lower noise and fast timing are important drivers

Shared interests and close collaboration with international DRD4

#### But important drawbacks:

- dark count rates after irradiation
- $\Rightarrow$  R&D on cryogenic operations
- ⇒ R&D on local cooling of SiPM with design of dedicated housing
- ⇒ R&D on implementing annealing to compensate for irradiation effects



### R&D on SiPMs

#### SiPM application across all future PP experiments $\rightarrow$ radiation hardness, lower noise and fast timing are important drivers

Main sensor

developments

from FBK and

**INFN** Italy

- SiPM single photon time resolution is dependent on sensor area
- Segmentation of active area into small pixels is a solution
- Each pixel instrumented with its own readout channel
- Signals can then be summed, or timing information combined



Acerbi, Fabio, et al. "Characterization of single-photon time resolution: from single SPAD to silicon photomultiplier." IEEE Transactions on Nuclear Science 61.5 (2014): 2678-2686.

- Major effect of radiation
  - Increase of dark count rate (DCR)
  - DCR strongly mitigated by lower temperature operation
  - Cooling is very effective in reducing DCR after irradiation up to ~1.10<sup>12</sup> n<sub>eq</sub>/cm<sup>2</sup>
  - Benefits of cooling seem to disappear at high fluences
- Annealing can produce partial recovery



### R&D on SiPMs for TOF Detectors

Develop a SiPM array for single-photon detection, with mm-scale pixelation, suitable for use in TOF prototypes

- R&D on SiPM detectors and electronics to provide:
  - mm-scale position sensitivity and fast timing
  - at very high rates expected with HL-LHC and future colliders
- Focus on the system aspects of combining:
  - SiPM arrays with radiation hardness, mm-scale pixelation, and cooling
  - The major effect of high irradiation levels will be elevated dark noise
  - Integrated with multichannel readout electronics such as the FastIC ASIC family
- SiPMs with segmentation providing several pixels per device
  - Event timing to ~10-20 ps will require close integration of the sensor and electronics
  - Power dissipation in the sensor at the very high rates anticipated will be large
  - Active cooling required for stable device gain and to reduce elevated dark noise
- Overall aim to achieve the best possible time resolution at required pixelation

TOF plays a pivotal role for experiments such as PANDA and CBM at FAIR and is considered for future upgrades of LHCb, ALICE, ATLAS/CMS, and at EIC and FCC-ee as well as in future kaon experiments and beam dump facilities

Shared interests and close collaboration with international DRD4

J. Lapingdton @ DRD4 Collaboration Meeting 2024

### MicroChannel Plate (MCP)

- Extremely good single-photon time resolution < 40 ps,</p>
- Custom pixelisation tailored for individual applications
- Drawbacks related to lifetime and rate capability

#### Photocathode aging due to ion feedback

#### Gain decreases at high photon rates ( $\tau$ = RC)

- □ 2-inch Photonis/Photek MCP-PMTs: ~1 MHz/cm<sup>2</sup> (with 10<sup>6</sup> gain)
- □ 1-inch Hamamatsu R10754 ≥10 MHz/cm<sup>2</sup>
- Rate capability also depends on MCP resistance, gain operation



R&D to investigate options of low-gain MCPs: MCP-HPD [JINST 13 C12005 2018]

#### UK R&D on MCP based photon detectors includes:

Developments of MCP-PMTs with increased lifetime with Photek Ltd (UK) Characterisation and tests of Photonis 2-inch MCP-PMT with 2 ALD layers Studies of Large Area Picosecond Photodetector (LAPPD)

Vacuum photon detectors have an essential future role  $\rightarrow$  rate capabilities and lifetime must be further developed

Hamamatsu, Photek, Photonis MCP-PMTs Tests for PANDA DIRC detector





#### Photonis ALD coated MCP-PMT >30 C/cm<sup>2</sup>



Shared interests and close collaboration with international DRD4

### Large Area Picosecond Photodetector (LAPPD)

#### Main R&D for future photodetectors will involve the time implementation

Large Area Picosecond Photodetector (LAPPD)

Micro Channel Plate photomultiplier, dimension 20 x 20 cm<sup>2</sup> Supplied by INCOM (US)

#### Advantages:

- Time resolution lower than 60 ps
- ➢ High gain (~ 10<sup>7</sup>)

Pixel size:

- capable of imaging single photons
- > Large tile benefit for instrumentation, more cost-effective

#### > Gen II LAPPD 97 @ Edinburgh

➢ Gen II LAPPD, pixel readout, 20 µm pores

Previous tests in Edinburgh

- Spectral response 160-650 nm
- ➤ 5 taps for independent voltage control of the photocathode and entry/exit of each MCP



#### Edinburgh progress

Custom readout board V0, 512 pixels

Pixel size:

3 mm pitch to pitch (2.9 x 2.9 mm<sup>2</sup> active area, 0.1 mm dead gap)

- ✓ Designed in Edinburgh by P.Gheewalla
- $\checkmark.$  Assembled to the LAPPD in Edinburgh

25 mm pitch to pitch (24 x 24 mm<sup>2</sup> active area, 1 mm dead gap)

Default INCOM readout board 64 pixels







The RICH group tested the LAPPD in 2023/2024 at CERN SPS, coupled to a multi-channel fast electronics chain (FastIC+picoTDC based) see <u>poster presented at the Pisa Meeting</u> High Rate Photodetector (HRPPD) supplied by INCOM soon in Edinburgh, with 10 μm pores, and directly coupled pixellated anode -> better time resolution and spatial footprint

Shared interests and close collaboration with international DRD4

### Transmission Dynodes: Enhancing Vacuum Photodetectors

- Ultra-thin transmission diamond dynode between photocathode and MCP
- Provides a barrier for ion backflow
  - $\rightarrow$  longer photocathode lifetime
- Provides electron gain
  - ightarrow Tighter pulse height distribution at lower overall gain
  - $\rightarrow$  Higher maximum count rate
- Future replace MCPs altogether with transmission dynode stack
  - → Excellent single photon spectrum
  - → Improved timing precision ~10 ps

Accepted for full submission to UKRI Early-Stage R&D scheme 2024 If fundings are granted → aim at the production of MCP-hybrid demonstrator with a single diamond layer (in collaboration with Photek Ltd)



Measured diamond secondary electron yield (reflection)

1500

Incident Electron Energy (eV)

1000

Bare CVD#1, #2

2000

20

500

20

3000

H/CVD#1

2500

### DRD6: Digital ECAL Concept

- Calorimeter samples energy between ~30 W absorber layers
- Analogue, e.g. CMS HGCAL (~ex-ILC), **sum energy** in 5x5 mm<sup>2</sup> Si cells
- Digital: count every individual particle in EM shower
  - Need ultra-small pixels! Ideally 1 particle/pixel → binary approach
  - EM shower core density at 500GeV ~100/mm<sup>2</sup>
  - Pixels <100x100µm<sup>2</sup> for no saturation
  - ~10<sup>12</sup> pixels for ECAL barrel



- Using CMOS MAPS, simpler construction, + expect lower cost
- A `tracking calorimeter', separates boosted decays, e.g.  $\tau, \pi^0 \rightarrow \gamma \gamma \dots$
- 20 X<sub>0</sub> prototype calorimeter in test beams



Si/W layer

interface boards

5mm

50 GeV 100 GeV

X pixel

150

200

100

stack

50

100

200

250

50

 bix ≻ 150

### (UK) DECAL Sensor Plans



- Original UK idea enabled use of fully efficient MAPS sensors
- Potentially reconfigurable sensor technology: outer tracker/preshower/ECAL
  - I.Kopsalis et al, NIM A1038 (2022) 166955 and P.P.Allport et al, Sensors 2022, 22(18) 6848
- Main R&D goals
  - Reduce ~20-100mW/cm<sup>2</sup> power consumption (collider-specific pulsing or ...)
  - Resolve identified issues with current DECAL sensor design
- Other ideas
  - 3d stack + semi-digital approach
  - Multi-threshold pixels
  - Increased configurability
  - ► Configurability, chip → FPGA
  - Modelling



<b>J</b>	NMOS	PMOS	NWELL COLLECTION ELECTRODE	
	PWELL	NWELL		PWELL NWELL
2	LOW	DOSE N-TY	PE IMPLANT	DEEP PWELL
7				
	P' EPITAXIAL	LAYER		
	P* SUBSTRA	TE		

- Collaborate with SLAC/Oregon, review overlaps/division of fundamental R&D goals
- Designer effort critical, cannot rely on effort from outside UK, e.g. Germany
   If we want to be involved in this activity in future, need access to recourse
  - If we want to be involved in this activity in future, need access to resources



### Dual readout Calorimeter - the principle

- Single device for EM and HAD calorimetry
- Resolution of hadronic energy measurement affected by fluctuations
  - •% energy carried by  $\pi^0 \rightarrow \gamma \gamma \; (f_{em})$
- Two readouts with different EM/hadronic response
  - Determine  $f_{em}$  and incident energy E.
- How? e.g. IDEA detector concept (FCC and CEPC CDRs)

- UK involved in IDEA collaboration, which has built and tested a dual-readout calorimeter prototype at CERN
- Spaghetti calorimeter, alternating clear (Cherenkov) and doped (Scintillating) fibres.
  - Cu absorber, 1 mm fibres, 1.5 mm pitch, readout by SiPM







Slides provided by Nigel Watson and Fabrizio Salvatore on behalf of UK-DRD6

### Technologies for Gas Detectors (DRD1)

Gas detectors (GDs) employed in many system categories (No other technology provides a similar diversity of uses):

✤ Muon systems, tracking, calorimetry, PID/TOF, ....

GD technologies include TPC, Gas Electron Multiplier (GEM), Micromegas, RPC, μ-RWELL, Straw tubes, Drift Chambers, Micro-Pattern Gaseous Detector (MPGD), THGEM .....

### All future facilities/detectors of 2030s and 2040s will use one or more GD technology

HL-LHC, EIC, PANDA/CMB @ FAIR, future kaon experiments, ee colliders, STCF, muon colliders, ...

### MAIN Drivers for GDs from facilities:

Main challenges at future facilities include large area coverage with precision timing info (DRDT 1.1) to ensure correct track-event association, and ability to cope with large particle fluxes using eco-gas mixture (DRDT 1.3).

Requirements for central tracking are **high-rate capability and excellent spatial resolution** for precision momentum measurement and PID with **minimal material budget and lightweight mechanical support** structures (DRDT 1.2)

### Liverpool Glass THGEMs

Novel Glass THGEMs developed at Liverpool (Patent GB2019563.2)

PI: K.Mavrokoridis@Liverpool.ac.uk

50cm x 50cm glass THGEM 1.1mm thick, 500μm ID holes, 800μm pitch hexagonal array



For more details: https://www.mdpi.com/207 6-3417/11/20/9450

A Novel Manufacturing Process for Glass THGEMs and First Characterisation in an Optical Gaseous Argon TPC



erc

Slide by K. Mavrokoridis

TPCs used in neutrino and dark matter sectors (DUNE, DarkSide-20k, ArDM, LZ....) 27

UNIVERSITY OF LIVERPOOL

### Glass THGEM Facility (

**MicroPattern Detector Facility** 

G-THGEM: https://www.mdpi.com/2076-3417/11/20/9450

A new abrasive machining facility in preparation at the University of Liverpool

Fully automated

Capable of machining 850mmx850mm active area Not limited to glass, any brittle material i.e. ceramic, carbon fibre etc.

Will lead glass THGEM R&D





G-THGEM with ITO electrodes and holes formed by abrasive machining.

Slide by K. Mavrokoridis

The abrasive machining manufacturing process has big impact on **28** neutrino and dark matter sectors, as well as in medical imaging

UNIVERSITY OF

LIVERPOOL

Substrate selection Typically nonductile substrate e.g. glass, ceramic

Electrode masking Defines electrode shape on top/bottom surfaces

Electrode deposition 150 Ohms/Sq ITO coating in this work

Machining masking Defines shape and location of THGEM holes

Abrasive Machining Abraded from both sides forming biconical through holes





### ANUBIS: full HL-LHC exploitation

- ANUBIS: Resistive Plate Chambers (RPC) to identify
  - Muons
  - Charged particles from long-lived particle decays
- R&D on RPCs for PID:
  - Eco-gases (intermediate rate & ageing requirements)
    - Essential requirement to realise ANUBIS
    - Current gas mixture (CO2, C2H2F4 i-C4H10, SF6):
       GWP ~ 1400 (!)
  - Optimisation for spatial resolution
  - Dedicated serial readout with data concentrators
    - Benefit from intermediate event rate
    - Substantially simpler infrastructure
  - Sealed RPC detectors (fill and forget)
    - Quality assurance techniques to probe longevity
- ANUBIS is a UK-lead international collaboration

Slides provided by Oleg Brandt and Pawel Majewski on behalf of UK-DRD1





### UNIVERSITY<sup>OF</sup> BIRMINGHAM



### Summary and outlook

- > Electron, muon, and charged hadron identification essential to target a broad Flavour Physics programme
- > UK has leadership and a track record in PID detectors providing a major contribution to the ESPPU
- > UK is leading exciting R&D in line with the main drivers identified by the ECFA Detector R&D roadmap
- UK R&D for HL-LHC is a very challenging programme with plenty of synergies with other R&D campaigns (detectors at EIC and future kaon experiments)
- UK is looking ahead to longer-term future projects (FCC, STCF, ...) to exploit R&D synergies and possibilities to expand its contribution to the next ESPP update



Special Thanks for their inputs to: Tom Blake, Oleg Brandt, David Evans, Jon Lapingdton, Pawel Majewski, Konstas Mavrokoridis, Rachel Montgomery, Paul Newman, Federica Oliva, Fabrizio Salvatore, Nigel Watson, Guy Wilkinson.

### Main R&D for PID detectors of 2030s/40s

From ECFA DRD Roadmap 2020

- 1. Enhance timing resolution and spectral range of photon detectors
  - crucial for fast timing in Cherenkov and TOF detectors
  - for operation with high particle fluxes and pile-up
  - > to extend the wavelength coverage of scintillation photons from noble gases and Cherenkov photons
- 2. Develop photosensors for extreme environments
  - essential for operation in the high-radiation environments at the HL-LHC, Belle II upgrade, EIC and FCC; and similarly for cryogenic operation.
- 3. Develop RICH and imaging detectors with low mass and high-resolution timing
  - required for PID at HL-LHC, Belle II upgrade, EIC, and FCC-ee
- 4. Develop compact high-performance time-of-flight detectors
  - > as complementary approach for PID at HL-LHC, EIC and FCC-ee

# UK contributions to the above R&D lines identified by the ESPPU $\rightarrow$ this talk

### LHCb Timeline

Most physics statistically rather than systematically or theoretically limited  $\rightarrow$  motivates high luminosity experiment. Upgrade1 aims to record 50fb<sup>-1</sup> by the end of Run4 Upgrade2 aims to record 300fb<sup>-1</sup> by end of HL-LHC.

**High Luminosity LHC** 



European Strategy Update 2020:

"The full potential of the LHC and the HL-LHC, including the study of flavour physics, should be exploited"

# The LHCb Upgrade 2

Physics programme aiming at huge improvements in precision on key flavour observables



#### Electron, muon, and charged hadron identification essential to target a broad Flavour Physics programme

European Strategy Update 2020:

"The full potential of the LHC and the HL-LHC, including the study of flavour physics, should be exploited"

# R&D for LHCb RICH LS3 & Upgrade 2



Beam Mirror Aerogel

- intense testbeam campaign ongoing
- test prototype electronics for LS3 with MaPMTs currently operated in the RICH Upgrade
- test candidates for photon detection in Upgrade II



#### S.Gambetta @ ICHEP 2024

## ARC @ FCC-ee: Radiators & Ray Tracing

### • $C_4F_{10}$ :

- Baseline assumption, well known from LHCb RICH1
- $n = 1.0014 \implies \theta_c = 53 \, {
  m mrad}$ , suitable for high momentum particles
- $C_4F_{10}$  is a greenhouse gas, plan to replace with suitable Novec gas, such as  $C_5F_{10}O$

• Aerogel:

- Well known as a RICH radiator, e.g. from ARICH at Belle II
- n = 1.01-1.10  $\implies \theta_c = 141$ -430 mrad, suitable at low momentum
- Very low thermal conductivity
  - Suitable to separate gas from detector, which must be cooled
  - Cherenkov photons come for "free" and are focused by the same mirror
- Drawback: Some loss of photons from scattering



Figure 6: Belle aerogel tiles (left) and aerogel transmission function (right).



Ray-tracing simulation of an ensemble of cells in the barrel region

## ARC @ FCC-ee: Performance (Simulation)



Kaon-proton separation significance in ARC barrel

Figure 10: Separation significance per track for  $\pi$ -K (left) and p-K (right)

- Gas (aerogel) provides over  $3\sigma$  pion-kaon separation in the range 10-50 GeV (2-10 GeV)
  - These plots do not include (small) effects of the magnetic field
- Combined, the aerogel and gas ensure excellent PID performance over the whole range of interest to flavour physics

A single cubic cell with gas, aerogel, cooling plate, vessel walls and mirror has been implemented, and it passed the overlap check!



Figure 14: Graphical display of a single cubic ARC cell. Vessel walls and cooling plate have been removed for easier visualisation.



Figure 7: Photon hits on photodetector

### **EIC Project Detector**





P. Jones @ PPAP Community Meeting June 2024

# Super Tau-Charm Facility (STCF)



• Silicon : CMOS MAPS

mass and small cell

### **Tentative Implementation Plan of STCF**

	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032-2047
Conception design CDR															
Key Technology R&D TDR															
Construction															
Operation															15 years

As presented by H.Peng at the STCF workshop held in January 2024

### **STCF: Progress of Technology R&D**



# **Particle Identification Detectors at STCF**

### **STCF detector**



### Endcap PID detector requirements

- >4 $\sigma \pi/K$  separation power at p≤2 GeV/c
- Compact structure, thickness<20 cm</li>
- Low material budget (<0.5 X<sub>0</sub>)
- High counting rate capability (~150 kHz/cm<sup>2</sup>)
- High radiation tolerance
- A TOF detector based on detection of internal reflected Cherenkov light technology (DIRC-like TOF) can meet these requirements.

The project plans RICH in the barrel and a **DIRC-like TOF (called the DTOF)** as end-cap PID detector in the forward region. The expected performance of the DTOF detector was simulated, showing its performance met the STCF PID requirements.

A full-size DTOF prototype was developed and tested using cosmic-ray. Single track time resolution found to be ~22 ps

Synergies with UK R&D: ongoing developments including also lifetime extended MCP-PMT, fast ASIC readout, ...



A full-size DTOF prototype was developed and tested using cosmic-ray. Single track time resolution found to be ~22 ps

### **Cherenkov radiator**

#### Heraeus Suprasil 312 synthetic fused silica

- High purity, transparency>99%@200 nm
- High radiation tolerance
- Thickness=15 mm, area ≈ 0.56 m<sup>2</sup>

### Some requirements

- Front&back surfaces, RMS <1 nm (0.75 nm, ☺)</li>
- Lateral surfaces, RMS <5 nm (not qualified ☺→absorber)</li>
- Top&button surfaces, absorber
- Thickness=15±0.1 mm, T<sub>max</sub>-T<sub>min</sub><25 μm</li>

Keep Cerenkov photon direction information

Reduce the misidentification of photon paths





Synergies with UK R&D: ongoing developments including also lifetime extended MCP-PMT, fast ASIC readout, ...

### **MCP-PMT**



#### Hamamatsu R10754 MCP-PMT ×42

- Sensitive area, 23×23 mm<sup>2</sup>
- Segmentation, 4×4 pixels
- Pixel size, 5.5×5.5 mm<sup>2</sup>
- spectral response range, 200-850 nm
- Quantum efficiency, ~25%@λ=400 nm
- Gain: >10<sup>6</sup>, uniformity~14% (σ/μ)
- Transit time spread: ~28 ps

#### Readout optimization to reduce crosstalk and ringing

- Optimize PCB routing and ground plane to ensure signal integrity and reduce distributed capacitance
- Separate high-voltage power supply and signal readout
- The decoupling capacitors are distributed around the MCP



Laser (width=60 ps) test, applying TOT and temperature correction



Synergies with UK R&D: ongoing developments including lifetime extended MCP-PMT, ASIC readout, ...

### DRD1 – Main Drivers from the facilities – Muon Systems

Summary of main facilities, the proposed technologies to address the main challenges, and the most stringent conditions expected in muon systems

Facility	Technologies	Challenges	Most challenging requirements at the experiment	
HL-LHC HL-LHC HL-LHC HL-LHC HL-LHC HIC-GEM, Micromegas, micro-pixel Micromegas, μ-RWELL, μ-PIC		Ageing and radiation hard, large area, rate capability, space and time resolution, miniaturisation of readout, eco-gases, spark-free, low cost	(LHCb): Max. rate: 900 kHz/cm <sup>2</sup> Spatial resolution: ~ cm Time resolution: O(ns) Radiation hardness: ~ 2 C/cm <sup>2</sup> (10 years)	
Higgs-EW-Top Factories (ee) (ILC/FCC-ee/CepC/SCTF)	GEM, μ-RWELL, Micromegas, RPC	Stability, low cost, space resolution, large area, eco-gases	(IDEA): Max. rate: 10 kHz/cm <sup>2</sup> Spatial resolution: ~60-80 μm Time resolution: O(ns) Radiation hardness: <100 mC/cm <sup>2</sup>	
Muon collider	Triple-GEM, μ-RWELL, Micromegas, RPC, MRPC	High spatial resolution, fast/precise timing, large area, eco-gases, spark-free	Fluxes: > 2 MHz/cm <sup>2</sup> ( $\theta$ <8 <sup>0</sup> ) < 2 kHz/cm <sup>2</sup> (for $\theta$ >12 <sup>0</sup> ) Spatial resolution: ~100 $\mu$ m Time resolution: sub-ns Radiation hardness: < C/cm <sup>2</sup>	
Hadron physics (EIC, AMBER, PANDA/CMB@FAIR, NA60+)	Micromegas, GEM, RPC	High rate capability, good spatial resolution, radiation hard, eco-gases, self-triggered front-end electronics	(CBM@FAIR): Max rate: <500 kHz/cm <sup>2</sup> Spatial resolution: < 1 mm Time resolution: ~ 15 ns Radiation hardness: 10 <sup>13</sup> neq/cm <sup>2</sup> /year	
FCC-hh (100 TeV hadron collider)	GEM, THGEM, μ-RWELL, Micromegas, RPC, FTM	Stability, ageing, large area, low cost, space resolution, eco-gases, spark-free, fast/precise timing	Max. rate 500 Hz/cm <sup>2</sup> Spatial resolution = 50 $\mu$ m Angular resolution = 70 $\mu$ rad ( $\eta$ =0) to get $\Delta p/p \le 10\%$ up to 20 TeV/c	

### **DUNE Phase II**

- R&D work ongoing for high pressure gas TPCs for large volume low occupancy neutrino physics scenario
- People actively pursuing readout electronics (generic low occupancy detector readout systems plus benchmarking frontend ASICs for gas detectors), gas mixtures, amplification stages (GEMs, THGEMs etc.)
- We have a UK-led test stand in a beam at Fermilab.

### MicroChannel Plate (MCP-PMT)

### High-speed single photon counting applications (<50ps TTS, <100ps RMS)

- $\hfill\square$  Similar to PMT  $\rightarrow$  dynode structure replaced by MCP
- $\hfill \ensuremath{\square}$  MCP is thin glass plate with an array of holes (capillaries) of 3-25  $\mu m$  diameter
- Continuous electron multiplication in thin glass capillaries
- □ High gain (10<sup>6</sup>) even in strong magnetic field (1T)

### Limitations:

- 1. Photo Cathode aging (feedback ions)
- 2. Rate capability ( $\tau$ =RC)

### **Atomic Layer Deposition (ALD) coated MCP**

- □ Ultra-thin films of resistive and emissive layers (MgO, Al<sub>2</sub>O<sub>3</sub>) applied to glass capillaries
- □ ALD-coated MCP improved lifetime up to ~10 C/cm<sup>2</sup> integrated anode charge (IAC)
- □ Rate capability still marginal (1-10 MHz/cm<sup>2</sup> depending on PMT size, and MCP resistance)
- $\rightarrow \rightarrow \rightarrow$  PMT sizes range from 1x1/2x2 inch<sup>2</sup> (Hamamatsu, Photonis, Photek)







Readout

### Lifetime and Rate Capability

#### PC aging due to ion feedback is a limitation

- $\hfill\square$  Aging of PC for MCP-PMT  $\rightarrow$  shorter lifetime than dynode PMTs
- □ Main issue for high intensity experiments is QE degradation
- □ Lifetime was poor (<200 mC/cm<sup>2</sup> IAC) until ~12 years ago
- $\hfill\square$  ALD coating of MCP pores  $\rightarrow$   $\sim 100x$  PC lifetime increase

#### □ No QE degradation for Photonis MCP-PMT (R2D2) >34 C/cm<sup>2</sup>

#### MCP-PMTs Gain decreases at high photon rates ( $\tau = RC$ )

- □ 2-inch MCP-PMTs:  $\sim$ 1 MHz/cm<sup>2</sup> (with 10<sup>6</sup> gain)
- □ 1-inch Hamamatsu R10754  $\geq$ 10 MHz/cm<sup>2</sup>
- Rate capability depends on MCP resistance
- □ Up to 20 MHz (for ~25 PE) in low gain operation (NIM A(2022)167330)

#### **Increasing rate capability in MCP-PMTs**

- **Lower MCP resistance (ranging at tens of M**Ω**)**
- □ Lower capacitance
- Low gain operation (for single photon detection)



### Task 4.4.2 - Develop a SiPM array for single-photon detection, with mm-scale pixelation, suitable for use in TOF prototypes

The focus will be on the system aspects of combining

- SiPM arrays with improved radiation hardness and dark count rate, mm-scale pixelation;
- State-of-the-art timing multichannel readout electronics;
- Integrated cooling;

with the overall aim of achieving the best possible time resolution

Deliverables	date*)	Principal Investigator	Group
4.4.2 Prototype of array of cooled, mm-scale segmented SiPMs with integrated readout, with report on design and performance	36	Karl Ziemons	Aachen
Milestones	date*)	David Gascon	Barcelona
VI4.4.2 Demonstrate performance for single-photon detection of SiPM arrays with FastIC readout	18	Eugenio Nappi	Bari
		Alberto Gola	FBK
*) date in months after project start		Jon Lapington	Leicester
		Christian Morel	Marseille

### Task 4.4.2 – R&D Challenges

#### **R/O electronics**

Vertical integration to optimize timing resolution by reducing the parasitic inductances and capacitances of the interconnections. Features close to the photosensors (active quenching, single spad control...)

Spa

A. Gola (PHOSE23 Workshop): FBK is investigating the potential of microTSVs to achieve single cell connection

#### **Optimization of SPTR with masking**

CHK-HD SiPMs is a variant of the NUV-HD SiPMs built to improve SPTR and detection efficiency

• Masking of outer regions of SPAD: Improve signal peaking and mask areas of SPAD with worse SPTR

A remarkable Single Photon Time Resolution of 28 ps FWHM was measured at Aachen (S. Gundacker)





SPTR FWHM (ps) vs Laser position (mm)

#### ~50 um SPAD pitch PAD SPAD SPAD SPAD array FEE ASIC CMOS wafer 50 um

Hybrid SiPM

#### **Microlenses (or metalens-based light** concentrators) to enhance radiation hardness

- Photons are focused on a smaller light-sensitive area within each microcell
- □ The silicon area sensitive to radiation damage is reduced
- □ The Fill Factor (FF), and thus the PDE of the SiPM microcells, is enhanced

### Task 4.4.3 - Develop lightweight mechanical supports for DIRC-type TOF detectors

- Cherenkov radiators typically large, heavy quartz plates.
- Mechanics require high geometrical precision.
- Prototype support developed using lightweight materials.
  - Adjustable and accurate positioning required.
  - Minimize distortion + support quartz, detectors, electronics.
  - Lightweight materials will be investigated.
- Prototype for performance verification.

Deliverables	date*)	Principal Investigator	Group			
D4.4.3 Prototype of a lightweight mechanical support for a DIRC-type TOF detector, with report on design and performance	36	Jochen Schwiening	GSI			
		Jianbei Liu	Hefei USTC			
Milestones	date*)	Guy Wilkinson	Oxford			
M4.4.3 Report on material choices and mechanical design for a lightweight TOF module	18		Oxioid			
*) date in months after project start						

### Task 4.4.3 – R&D Challenges

#### **Mechanical Supports**

Mechanical supports for large, heavy, fragile Cherenkov radiators

 Typically a set of highly polished quartz plates several tens of square metres in area

Mechanical supports must be lightweight and minimize

- contact with optical surfaces ٠
- Material in detector acceptance ٠



# **TORCH** prototype optical design $\theta_z = 0.45 \text{ rad}$ $\theta_z = 0.85 \text{ rad}$ $\theta_z$

#### **Optical Coupling**

High precision optical coupling with other optical components to the detectors

Optical components require adjustable and • highly accurate positioning

Supports must keep geometrical distortion to a minimum while supporting:

- Large overall weight of the quartz ٠
- Services such as detectors and electronics

#### **Lightweight materials**

Lightweight materials such as carbon-fibre based composites necessary

- Removable handling jigs for installation
- Prototype lightweight mechanical structure developed and verified.



### Task 4.4.4 - Develop techniques for measuring the optical properties of optical components for TOF detectors

- Characterization of the quartz Cherenkov radiators.
  - Radiator optical specification is demanding.
  - Challenging to manufacture and difficult to measure.
- Facilities already exist within the project partners.
  - These will be available for task collaborators.
- Precision measurement will be further developed.

Deliverables	date*)	Principal Investigator	Group
D4.4.4 Completion of commissioning of an optical laboratory for characterizing the performance of a DIRC-style quartz radiator plate	36	Jianbei Liu	Hefei USTC
		Jochen Schwiening	GSI
Milestones	date*)	Suat Ozkorucuklu	Istanbul
M4.4.4 Report on progress in setting up optical laboratory for characterizing TOF radiator	18		
		Guy Wilkinson	Oxford
*) date in months after project start		Mauro Piccini	Perugia INFN
		Amur Margaryan	Yerevan

### Task 4.4.4 – R&D Challenges

#### **Characterization of Cherenkov radiators**

Techniques for characterization of the quartz Cherenkov radiators

Techniques for coupling of optical components Radiator requirements include:

- Very high level of polish → very low surface roughness
- High degree planarity
- Difficult to achieve and to accurately measure with the required precision

Bevelled quartz radiator plate

#### TORCH prototype optical design



### Further precision measurements

Further develop techniques for higher precision.

Additional measured parameters will include:

 Planarity, optical transmission, scattering, defect size and density, radiation darkening



#### Quartz focusing block

#### **Existing Facilities**

Facilities already exist within the project partners

- Existing temperature-stabilized optical lab
- Polarized laser beams with six different wavelengths
- → coefficient of total internal reflection, bulk attenuation of TOF/DIRC bars or plates

Available on request to collaborators within Task 4.4.4

### Granularity and segmentation

- FBK proposing segmented large area SiPMs as next stage
  - Strip SiPMs

"SPTR and CRT performance is degraded when reading out SiPMs with large areas.

A possible solution can be the segmentation of the active area into small pixels"

"The goal for FBK is upgrading ... by developing TSVs, micro-TSV and Backside Illuminated SiPMs"

*"This will allow high-density interconnections to the front-end and high-segmentation"* 



Example of segmented SiPM layout: a 3x3 mm2 active area is divided in 10 0.3x3 mm2 strip-SiPMs.

Alberto Gola - Status and perspectives of SiPMs at FBK – CERN 2023

### Power dissipation and cooling

- Rate or lifetime not an issue for SiPM
  - Power dissipation and cooling likely required
  - Energy dissipated per event =  $\frac{C_{cell}}{2} (V_{op}^2 V_{ov}^2)$
  - 600 Mevent/s ≈ 21 mW/cm<sup>2</sup>
- FBK have made interesting developments in cooling technology
  - 2.5D integration allows micro cooling channels integrated inside a passive interposer



### Electronics compatibility

- FastIC family of electronics designed for SiPMs
- FastIC developments from the have already superseded previous technologies e.g. NINO
- Future FastIC developments include FastICpix:
  - Aim to exploit optimal segmentation of SiPM
  - Optimization for a given power budget
  - Investigation of new circuit topologies
  - 3D integration
- FastlCpix aim:
  - Optimal and adaptable segmentation
  - Using a hybrid detector



### Temperature controlled dark box SiPM testing from -20 °C to +40 °C



# SiPMs for CTA SST Camera

### Pixellated SiPM tile - TARGET ASIC waveform capture

Connection to the backplane: raw data, trigger, clock signals, electronics power (12 V) and SiPM bias voltage (~70 V) Power board provides low voltages, SiPM bias voltage trimming and monitoring Shielding for all switching components and ASICs SiPM bias voltage Low-voltage power on separate cable to buffer Primary board and Copper heat-sink auxiliary boards each arrangement to contain 32 channels of CHEC-S SIPM: focal plane plate readout Hamamatsu S12642-1616PA-50 TARGET-C and T5TEA ASICs Amplifier and shaper provide 16 channels of digitisation 64 camera circuits for optimal **pixels** and triggering. Slow ADCs provide signal-to-noise a parallel readout stream for Cables used to remove SiPM monitoring of DC signal radius of curvature in Tile component focal plane Samtec individually shielded ~50 coaxial ribbon cables for mm analogue signals Temperature sensor Buffer circuits for noise immunity

**UK DRD-4 Meeting** 

3 mm

Gap

87% geometric

93% geometric fill factor possible with 6 mm pixels and same

gaps, tile reduces to 50 mm x 50 mm

Depth of ~3.5 mm (including base PCB) 50

fill factor

50-µm Cells with

Thin-Film Coating

Through

(TSV)

Silicon Via

### ASIC FEE experience – NINO32 design

Pixellated MCP detector using NINO + HPTDC – forerunner to TORCH prototype

